

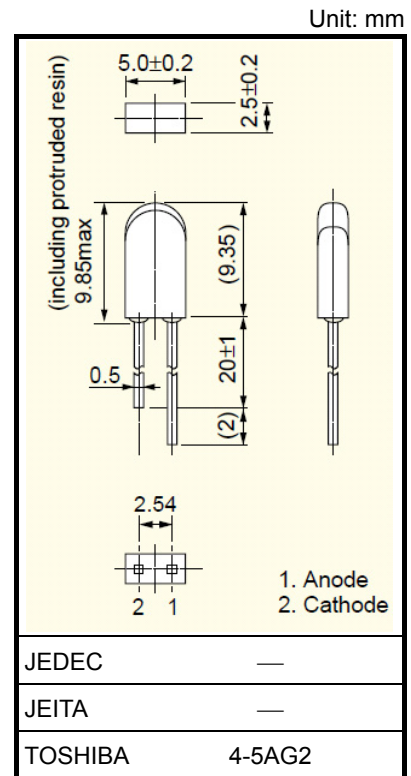
TOSHIBA InGaAlP LED
TLGE33TP(F)

Panel Circuit Indicators

- Lead(Pb)-free products (lead: Sn-Ag-Cu)
- 2.5x5mm package
- InGaAlP technology
- Transparent lens
- Excellent low current light output
- High intensity light emission
- Excellent low current light output
- Applications: dashboard displays, various indicator
- Stopper lead type is also available

Lineup

Product Name	Color	Material
TLGE33TP(F)	green	InGaAlP



Absolute Maximum Ratings (Ta = 25°C)

Weight: 0.23 g (Typ.)

Product Name	Forward Current I _F (mA)	Reverse Voltage V _R (V)	Power Dissipation P _D (mW)	Operating Temperature T _{opr} (°C)	Storage Temperature T _{stg} (°C)
TLGE33TP(F)	50	4	120	-40~100	-40~120

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook (“Handling Precautions”/“Derating Concept and Methods”) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Electrical and Optical Characteristics (Ta = 25°C)

Product Name	Typ. Emission Wavelength (Note)			Luminous Intensity I _v (Note)			Forward Voltage V _F			Reverse Current I _R		
	λ _d	λ _p	Δλ	I _F	Min	Typ.	I _F	Typ.	Max	I _F	Max	V _R
TLGE33TP(F)	571	(574)	17	20	476	1300	20	2.0	2.4	20	50	4
Unit	nm			mA	mcd		mA	V		mA	μA	V

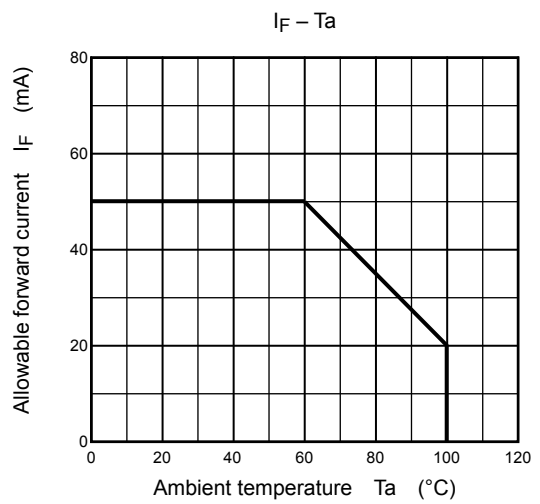
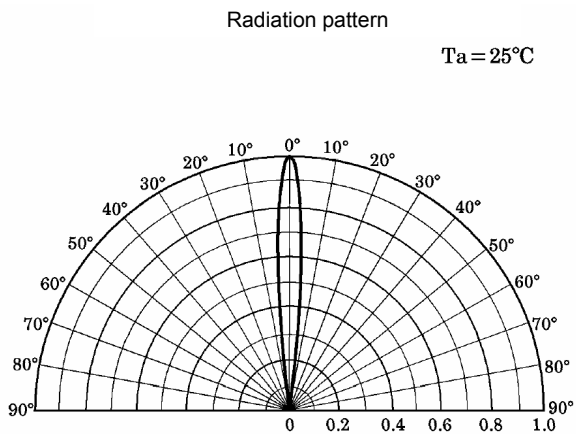
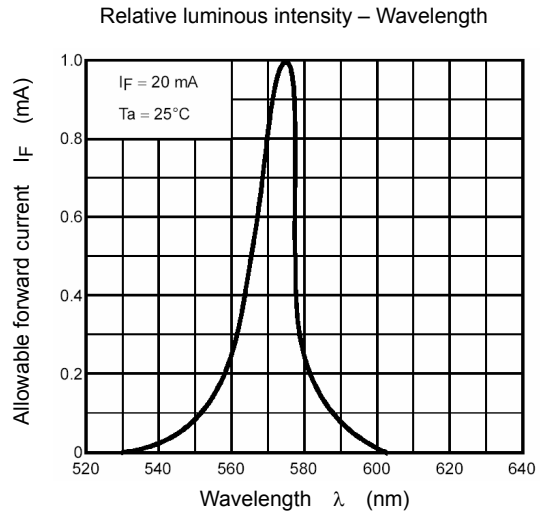
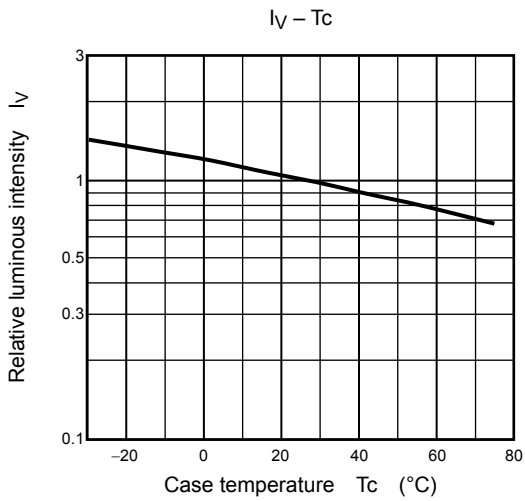
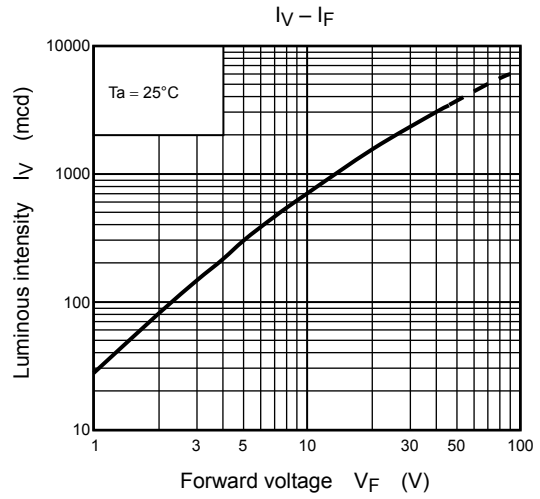
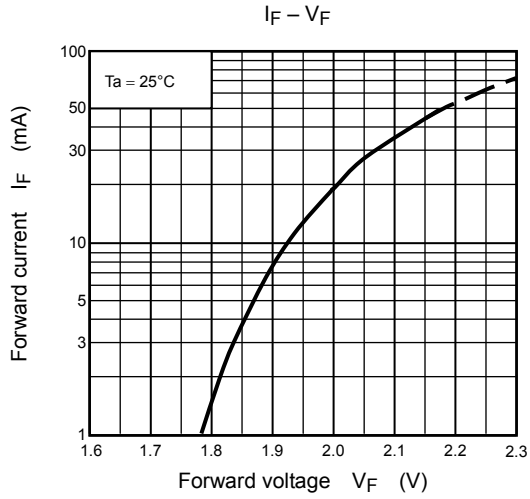
Note: Lamps are classified into the following ranks according to their luminous intensity. Each packing box includes single Luminous Intensity class. I_v : R: 476-1290mcd, S: 850-2300mcd, T: 530mcd -, λ_d 1: 565-573nm, 2: 569-576nm

Precautions

Please be careful of the following:

- Soldering temperature: 260°C max, soldering time: 3 s max (soldering portion of lead: up to 1.6 mm from the body of the device)
- If the lead is formed, the lead should be formed up to 1.6 mm from the body of the device without forming stress to the resin. Soldering should be performed after lead forming.
- This visible LED lamp also emits some IR light. If a photodetector is located near the LED lamp, please ensure that it will not be affected by this IR light.

TLGE33TP(F)



RESTRICTIONS ON PRODUCT USE

20070701-EN

- The information contained herein is subject to change without notice.
- TOSHIBA is continually working to improve the quality and reliability of its products. Nevertheless, semiconductor devices in general can malfunction or fail due to their inherent electrical sensitivity and vulnerability to physical stress. It is the responsibility of the buyer, when utilizing TOSHIBA products, to comply with the standards of safety in making a safe design for the entire system, and to avoid situations in which a malfunction or failure of such TOSHIBA products could cause loss of human life, bodily injury or damage to property.
In developing your designs, please ensure that TOSHIBA products are used within specified operating ranges as set forth in the most recent TOSHIBA products specifications. Also, please keep in mind the precautions and conditions set forth in the "Handling Guide for Semiconductor Devices," or "TOSHIBA Semiconductor Reliability Handbook" etc.
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